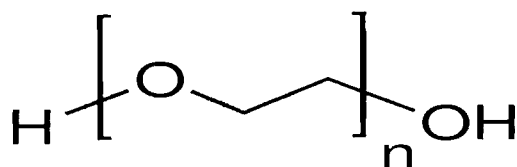


ABSTRACT

BARRIER CHEMICAL MECHANICAL PLANARIZATION COMPOSITION AND METHOD OF USE THEREOF

A barrier chemical mechanical planarization polishing composition is provided
5 that includes suitable chemical additives. The suitable chemical additives are organic
polymer molecules containing ethylene oxide repeating units having the general
molecular structure of



10 where n refers to the total numbers of the repeating unit ranging from 6,818 to 181,817;
and the molecular weights of polyethylene oxide range from 100,000 to 8,000,000. There
is also provided a chemical mechanical polishing method using the barrier chemical
mechanical planarization polishing composition.

15 Figure 1

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